Sputter evaporation

Description

Magnetron sputtering deposition, use with DC or RF, uses a closed magnetic field to trap electrons, enhancing both the efficiency of the initial ionization process and allowing plasma to be generated at lower pressures which reduces both background gas incorporation in the growing film and energy loses in the sputtered atom through gas collisions.

Odem Sputter system for R&D Application based on magnetron sputtering principle allows to deposition of various metals and insulators.

Specifications / Capabilities

- Substrate sizes up to 5"x5".
- Two 2" RF guns and one 2" DC gun
- Ultimate pressure: 5x10^-7 mbar.
- Introducing gass system: Two mass flow controllers.

Standard tolerance: 10-15%

Materials

Various metals and insulators such as Au, Ti, Cr, TiN, TiO2, Cr, SiO2, Mg F2, and others...

Link

http://www.odemltd.com/

http://www.odemltd.com/RfampD_Application%2C_3x2%22_Guns